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PRODUCT CHANGE NOTIFICATION

PCN: PCN162504 **Date:** 24 June 2016

Subject: Qualification of an Alternate Mold Compound and Die Attach Epoxy for TSOP and FBGA/MCP packages.

Change Type: Major

Description of Change:

Cypress announces the qualification of an alternate die attach epoxy (Sumitomo CRM-1150B) and/or mold compound (Sumitomo G600B/SB) for all TSOP packages, and an alternative die attach epoxy (Sumitomo CRM-1577DB) for all FBGA and MCP packages assembled at Cypress Bangkok. The qualification will enable Cypress to continually provide world-class services and meet our customers' stringent quality and reliability requirements. TSOP and FBGA/MCP packages assembled at Cypress Bangkok will use the following Bill of Materials (BOM).

	TSOP			
	Current BOM	**New BOM 1** (Excludes NAND and GL-P/GL-N high density products)	**New BOM 2** (Only GL-P and GL-N high density products[2])	**New BOM 3** Only NAND products)
Die Attach Epoxy / DA Film	Ablestik 8340 / Hitachi DA Film	Ablestik 8340 or CRM-1150B	Ablestik 8340 or CRM-1150B	Hitachi DA Film
Mold Compound	CEL 9200HF10 CEL 9200HF10-U[1]	CEL 9200HF10-U[1] or CEL 9200HF10 or G600B or G600SB[1]	CEL 9200HF10-U[1]	EL-9200HF10 or G600B

*Note[1]: "-U" & "SB" are low alpha grade mold compound.
*Note[2]: GL-P/GL-N high density products include 128M / 256M / 512M and 1G devices.

	FBGA/MCP	
	Current BOM	**New BOM**
Die Attach Epoxy	Henkel QMI 546	Henkel QMI 546 or Sumitomo CRM-1577DB

There are no changes to ordering part numbers. Product datasheets remain the same and can be downloaded from the Cypress Website (www.cypress.com).

Benefit of Change:
The addition of Sumitomo CRM-1150B and CRM-1577DB die attach epoxy and G600B/SB mold compound allows the increase of assembly material availability and flexibility.

Affected Part Numbers: 2269
Affected Parts:
See the attached 'Affected Parts List' file for a list of all part numbers affected by this change. Note that any new parts that are introduced after the publication of this PCN may also be manufactured with CRM-1150B/CRM-1577DB die attach epoxy and G600B/SB mold compound at Cypress Bangkok facility.

Qualification Status:
The change has been qualified through a series of tests documented in Qualification Test Plans (QTPs) 153704 and 153705. The qualification reports can be found as attachments to this notification.

Sample Status:
Qualification samples are not built ahead of time for all part numbers affected by this change. Please contact your local Cypress Sales representative for sample availability as soon as possible, but within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:
Effective 90 days from the date of this notification or upon customer approval, all shipments of the affected part numbers in the attached file will be manufactured with the combination of the BOM shown above.

Anticipated Impact:
Products manufactured with Sumitomo CRM-1150B/CRM-1577DB die attach epoxy and Sumitomo G600B/SB mold compound are completely compatible with existing product from a functional, parametric, and quality performance perspective.

Cypress recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:
There will be no changes to the part number. Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

Response Required:
No response is required

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration